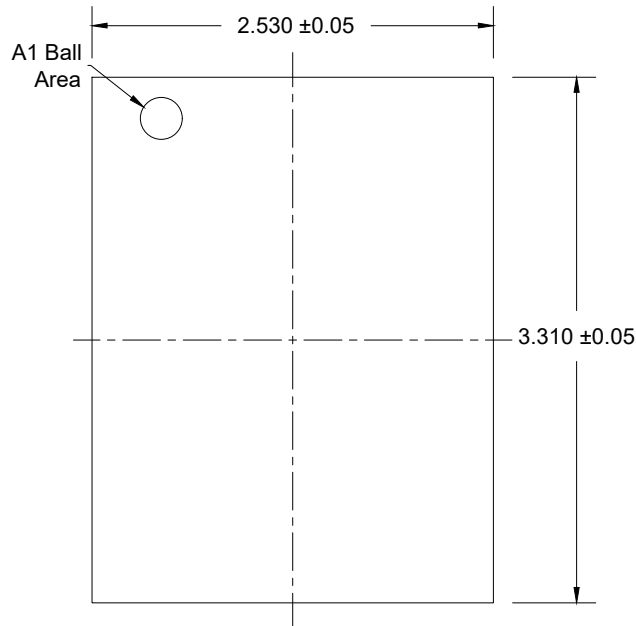
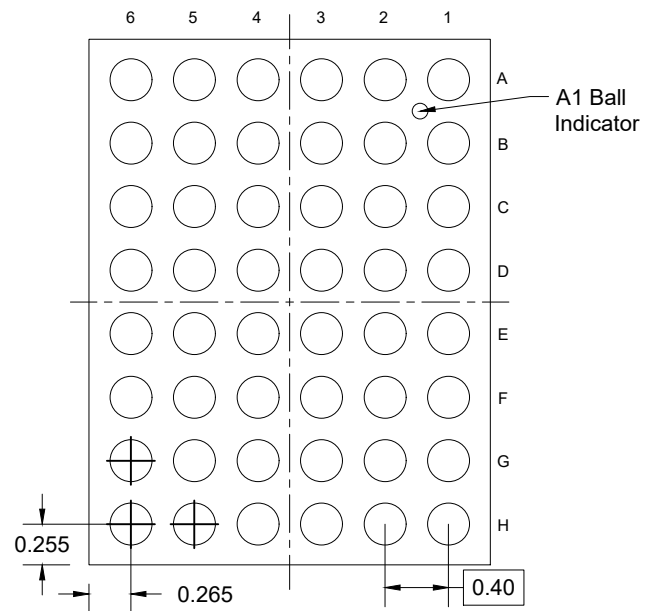
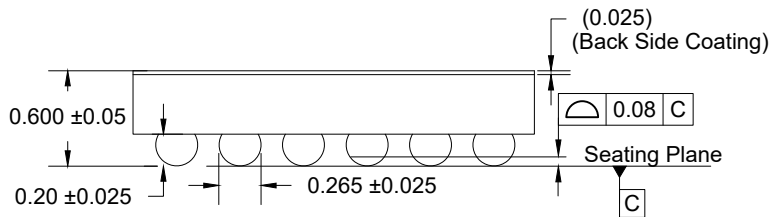




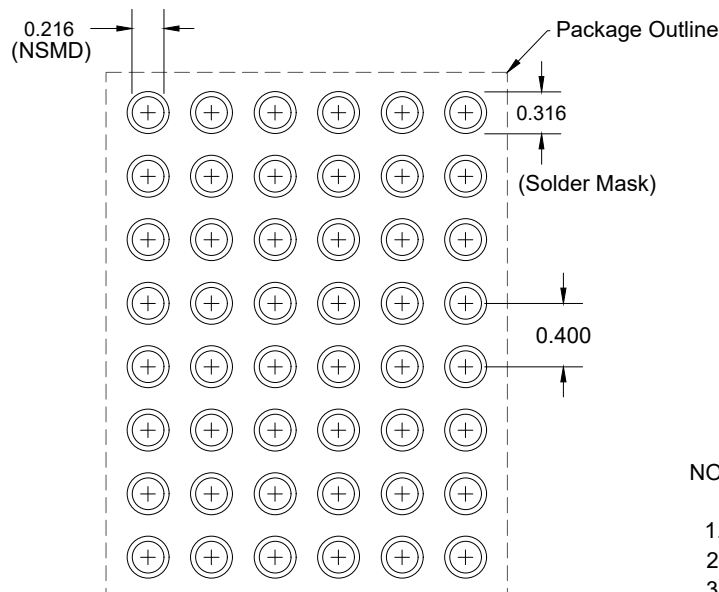
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN
(PCB Top View, NSMD Design)

NOTES:

1. JEDEC compatible.
2. All dimensions are in mm and angles are in degrees.
3. Use ±0.05 mm for the non-toleranced dimensions.
4. Numbers in () are for references only.
5. Pre-reflow solder ball diameter is Ø0.25 mm.
6. UBM diameter is Ø0.24 mm.